Raise3D DF2 Technical Specifications

The Raise3D DF2 solution is a Digital Light Printing (DLP) system offering speed, quality, exceptional reliability and efficient workflow via RFID. It is designed for engineering prototyping, manufacturing aids, and low-volume production using a wide variety of high-performance

| Printer | | Raise3D DF2 | |
|---------------------------|--|--|--|
| | Print Technology | DLP | |
| | Build Volume (W \times D \times H) | 200 × 112 × 300 mm (7.87 × 4.41 × 11.8 inch) | |
| | XY Resolution | 2560 × 1440 | |
| | Max Z Workload | 10 kg | |
| | Layer Height | 50-100 micron | |
| Printer | Max Printing Speed | 25 mm/h (0.1 mm per layer) | |
| Hardware | Resin Level Detection | Yes | |
| | Auto Resin Refill | Yes | |
| | Control Panel | Touch Screen (1920 × 720, Magic Layout) | |
| | Level Calibration | Calibrated in Factory | |
| | Chamber Heating | Yes (Max 40°C) | |
| | Raise3D Standard | White | |
| | Raise3D High Detail | Apricot | |
| Resins | Raise3D Tough 2K | Grey | |
| (Available | Raise3D Rigid 3K | Grey | |
| Options) | Raise3D High Clear | Coming Soon | |
| | Raise3D High Temperature | Coming Soon | |
| | Open Resin Program | Coming Soon | |
| | Connectivity | Wi-Fi, LAN, USB port × 2, Live camera | |
| | Network | Ethernet, Wireless 802.11 b/g/n | |
| Software and | Slicing Software | ideaMaker | |
| Network | Remote Management Software | RaiseCloud | |
| | Supported File Types | STL/ OBJ/ 3MF/ OLTP | |
| | Supported OS | WINDOWS/ macOS/ LINUX | |
| | Power Supply Input | 100-240VAC, 50/60 Hz 230V @ 3.3A | |
| | Operating Ambient Temperature | 15 - 30°C, 10 - 90% RH Non-Condensing (HOLD) | |
| | Storage Temperature | -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD) | |
| Operation and Shipping | Machine Size (W \times D \times H) | 450 × 400 × 730 mm (17.7 × 15.7 × 28.7 inch) | |
| | Weight | 40 kg (Net Weight) | |
| | | 59.4 kg (Gross Weight) | |
| | Shipping Dimensions | 710 × 595 × 980 mm (28.0 × 23.4 × 38.6 inch) | |



Raise3D DF Wash & DF Cure Technical Specifications

The Raise3D DF2 solution is a Digital Light Printing (DLP) system offering speed, quality, exceptional reliability and efficient workflow via RFID. It is designed for engineering prototyping, manufacturing aids, and low-volume production using a wide variety of high-performance

| Machine | Raise3D DF Wash | | |
|--------------|--|--|--|
| Hardware | Washing Tank Volume | 14 L | |
| | Max Washing Volume | 200 × 112 × 300 mm (7.87 × 4.41 × 11.8 inch) | |
| | Compatible Solvent | IPA, Water, TPM | |
| | RFID Print Platform | Supported | |
| | Automated Waste Drainage | Yes | |
| | Power Supply Input | 100-240VAC, 50/60 Hz, 0.55 A/230VAC | |
| | Operating Ambient Temperature | 10°C-35°C | |
| | Storage Temperature | -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD) | |
| Operation | Machine Gross Weight | 45.4 kg | |
| and Shipping | Grey Tank Gross Weight | 0.65 kg | |
| 11 3 | Machine Size (W \times D \times H) | 400 × 410 × 646 mm (15.7 × 16.1 × 25.4 inch) | |
| | Machine Shipping Dimension | 725 × 585 × 915 mm (28.5 × 23.0 × 36.0 inch) | |
| | Grey Tank Shipping Dimension | 407 × 247 × 349 mm (16.0 × 9.7 × 13.7 inch) | |

| Machine | Raise3D DF Cure | | |
|---------------------------|--|--|--|
| Hardware | Max Curing Size | φ 230 x 300 mm (φ 9 x 11.8 inch) | |
| | Curing Source | LED (365nm, 385nm, 405nm Mixed) | |
| | | Air Heating (Max Temperature 120°C) | |
| Operation and Shipping | Power Supply Input | 100-240 V AC, 50/60 Hz, 230 V AC @ 2.6 A | |
| | Operating Ambient Temperature | 10-35℃ | |
| | Storage Temperature | -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD) | |
| | Net Weight | 31.95 kg | |
| | Gross Weight | 45.5 kg | |
| | Machine Size (W \times D \times H) | 490 × 400 × 610 mm (19.3 × 15.7 × 24.0 inch) | |
| | Shipping Dimension (W \times D \times H) | 725 × 585 × 850 mm (28.5 × 23.0 × 33.5 inch) | |

